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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details

Product Status	Active
Architecture	MCU, FPGA
Core Processor	Quad ARM® Cortex®-A53 MPCore™ with CoreSight™, Dual ARM®Cortex™-R5 with CoreSight™, ARM Mali™ -400 MP2
Flash Size	-
RAM Size	256KB
Peripherals	DMA, WDT
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	600MHz, 667MHz, 1.5GHz
Primary Attributes	Zynq@UltraScale+™ FPGA, 926K+ Logic Cells
Operating Temperature	0°C ~ 100°C (Tj)
Package / Case	1924-BBGA, FCBGA
Supplier Device Package	1924-FCBGA (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xczu17eg-3ffve1924e

Recommended Operating Conditions

 Table 2: Recommended Operating Conditions⁽¹⁾⁽²⁾

Symbol	Description	Min	Typ	Max	Units
Processor System					
V _{CC_PSINTFP} ⁽³⁾	PS full-power domain supply voltage.	0.808	0.850	0.892	V
	For -1LI and -2LE (V _{CCINT} = 0.72V) devices: PS full-power domain supply voltage.	0.808	0.850	0.892	V
	For -3E devices: PS full-power domain supply voltage.	0.873	0.900	0.927	V
V _{CC_PSINTLP}	PS low-power domain supply voltage.	0.808	0.850	0.892	V
	For -1LI and -2LE (V _{CCINT} = 0.72V) devices: PS low-power domain supply voltage.	0.808	0.850	0.892	V
	For -3E devices: PS low-power domain supply voltage.	0.873	0.900	0.927	V
V _{CC_PSAUX}	PS auxiliary supply voltage.	1.710	1.800	1.890	V
V _{CC_PSINTFP_DDR} ⁽³⁾	PS DDR controller and PHY supply voltage.	0.808	0.850	0.892	V
	For -1LI and -2LE (V _{CCINT} = 0.72V) devices: PS DDR controller and PHY supply voltage.	0.808	0.850	0.892	V
	For -3E devices: PS DDR controller and PHY supply voltage.	0.873	0.900	0.927	V
V _{CC_PSADC}	PS SYSMON ADC supply voltage relative to GND_PSADC.	1.710	1.800	1.890	V
V _{CC_PSPLL}	PS PLL supply voltage.	1.164	1.200	1.236	V
V _{PS_MGTRAVCC}	PS-GTR supply voltage.	0.825	0.850	0.875	V
V _{PS_MGTRAVTT}	PS-GTR termination voltage.	1.746	1.800	1.854	V
V _{CCO_PSDDR} ⁽⁴⁾	PS DDR I/O supply voltage.	1.06	–	1.575	V
V _{CC_PSDDR_PLL}	PS DDR PLL supply voltage.	1.710	1.800	1.890	V
V _{CCO_PSIO} ⁽⁵⁾	PS I/O supply.	1.710	–	3.465	V
V _{PSIN}	PS I/O input voltage.	–0.200	–	V _{CCO_PSIO} + 0.200	V
	PS DDR I/O input voltage.	–0.200	–	V _{CCO_PSDDR} + 0.200	
V _{CC_PSBATT} ⁽⁶⁾	PS battery-backed RAM and battery-backed real-time clock (RTC) supply voltage.	1.200	–	1.500	V
Programmable Logic					
V _{CCINT}	PL internal supply voltage.	0.825	0.850	0.876	V
	For -1LI and -2LE (V _{CCINT} = 0.72V) devices: PL internal supply voltage.	0.698	0.720	0.742	V
	For -3E devices: PL internal supply voltage.	0.873	0.900	0.927	V
V _{CCINT_IO} ⁽⁷⁾	PL internal supply voltage for the I/O banks.	0.825	0.850	0.876	V
	For -1LI and -2LE (V _{CCINT} = 0.72V) devices: PL internal supply voltage for the I/O banks.	0.825	0.850	0.876	V
	For -3E devices: PL internal supply voltage for the I/O banks.	0.873	0.900	0.927	V
V _{CCBRAM}	Block RAM supply voltage.	0.825	0.850	0.876	V
	For -3E devices: block RAM supply voltage.	0.873	0.900	0.927	V
V _{CCAUX}	Auxiliary supply voltage.	1.746	1.800	1.854	V

Table 2: Recommended Operating Conditions⁽¹⁾⁽²⁾ (Cont'd)

Symbol	Description	Min	Typ	Max	Units
V _{CCO} ⁽⁸⁾	Supply voltage for HD I/O banks.	1.140	–	3.400	V
	Supply voltage for HP I/O banks.	0.950	–	1.900	V
V _{CCAUX_IO} ⁽⁹⁾	Auxiliary I/O supply voltage.	1.746	1.800	1.854	V
V _{IN} ⁽¹⁰⁾	I/O input voltage.	–0.200	–	V _{CCO} + 0.200	V
I _{IN} ⁽¹¹⁾	Maximum current through any PL or PS pin in a powered or unpowered bank when forward biasing the clamp diode.	–	–	10	mA
GTH or GTY Transceiver					
V _{MGTAVCC} ⁽¹²⁾	Analog supply voltage for the GTH or GTY transceiver.	0.873	0.900	0.927	V
V _{MGTAVTT} ⁽¹²⁾	Analog supply voltage for the GTH or GTY transmitter and receiver termination circuits.	1.164	1.200	1.236	V
V _{MGTVCCAUX} ⁽¹²⁾	Auxiliary analog QPLL voltage supply for the transceivers.	1.746	1.800	1.854	V
V _{MGTAVTTRCAL} ⁽¹²⁾	Analog supply voltage for the resistor calibration circuit of the GTH or GTY transceiver column.	1.164	1.200	1.236	V
VCU					
V _{CCINT_VCU}	Internal supply voltage for the VCU.	0.825	0.850	0.876	V
	For -1LI and -2LE (V _{CCINT} = 0.72V) devices: Internal supply voltage for the VCU.	0.825	0.850	0.876	V
	For -3E devices: Internal supply voltage for the VCU.	0.873	0.900	0.927	V

Speed Grade Designations

Since individual family members are produced at different times, the migration from one category to another depends completely on the status of the fabrication process for each device. [Table 26](#) correlates the current status of the Zynq UltraScale+ MPSoC on a per speed grade basis. See [Table 3](#) for operating voltages listed by speed grade.

Table 26: Speed Grade Designations by Device

Device	Speed Grade, Temperature Ranges, and V_{CCINT} Operating Voltages		
	Advance	Preliminary	Production
XCZU2CG	-2LE ($V_{CCINT} = 0.85V$) -2LE ($V_{CCINT} = 0.72V$) -1LI ($V_{CCINT} = 0.85V$) -1LI ($V_{CCINT} = 0.72V$)		-2E ($V_{CCINT} = 0.85V$) -2I ($V_{CCINT} = 0.85V$) -1E ($V_{CCINT} = 0.85V$) -1I ($V_{CCINT} = 0.85V$)
XCZU2EG	-2LE ($V_{CCINT} = 0.85V$) -2LE ($V_{CCINT} = 0.72V$) -1LI ($V_{CCINT} = 0.85V$) -1LI ($V_{CCINT} = 0.72V$)		-2E ($V_{CCINT} = 0.85V$) -2I ($V_{CCINT} = 0.85V$) -1E ($V_{CCINT} = 0.85V$) -1I ($V_{CCINT} = 0.85V$)
XCZU3CG	-2LE ($V_{CCINT} = 0.85V$) -2LE ($V_{CCINT} = 0.72V$) -1LI ($V_{CCINT} = 0.85V$) -1LI ($V_{CCINT} = 0.72V$)		-2E ($V_{CCINT} = 0.85V$) -2I ($V_{CCINT} = 0.85V$) -1E ($V_{CCINT} = 0.85V$) -1I ($V_{CCINT} = 0.85V$)
XCZU3EG	-2LE ($V_{CCINT} = 0.85V$) -2LE ($V_{CCINT} = 0.72V$) -1LI ($V_{CCINT} = 0.85V$) -1LI ($V_{CCINT} = 0.72V$)		-2E ($V_{CCINT} = 0.85V$) -2I ($V_{CCINT} = 0.85V$) -1E ($V_{CCINT} = 0.85V$) -1I ($V_{CCINT} = 0.85V$)
XCZU4CG	-2E ($V_{CCINT} = 0.85V$) -2I ($V_{CCINT} = 0.85V$), -2LE ($V_{CCINT} = 0.85V$) -1E ($V_{CCINT} = 0.85V$), -1I ($V_{CCINT} = 0.85V$) -1LI ($V_{CCINT} = 0.85V$) -2LE ($V_{CCINT} = 0.72V$), -1LI ($V_{CCINT} = 0.72V$)		
XCZU4EG	-3E ($V_{CCINT} = 0.90V$), -2E ($V_{CCINT} = 0.85V$) -2I ($V_{CCINT} = 0.85V$), -2LE ($V_{CCINT} = 0.85V$) -1E ($V_{CCINT} = 0.85V$), -1I ($V_{CCINT} = 0.85V$) -1LI ($V_{CCINT} = 0.85V$) -2LE ($V_{CCINT} = 0.72V$), -1LI ($V_{CCINT} = 0.72V$)		
XCZU4EV	-3E ($V_{CCINT} = 0.90V$), -2E ($V_{CCINT} = 0.85V$) -2I ($V_{CCINT} = 0.85V$), -2LE ($V_{CCINT} = 0.85V$) -1E ($V_{CCINT} = 0.85V$), -1I ($V_{CCINT} = 0.85V$) -1LI ($V_{CCINT} = 0.85V$) -2LE ($V_{CCINT} = 0.72V$), -1LI ($V_{CCINT} = 0.72V$)		
XCZU5CG	-2E ($V_{CCINT} = 0.85V$) -2I ($V_{CCINT} = 0.85V$), -2LE ($V_{CCINT} = 0.85V$) -1E ($V_{CCINT} = 0.85V$), -1I ($V_{CCINT} = 0.85V$) -1LI ($V_{CCINT} = 0.85V$) -2LE ($V_{CCINT} = 0.72V$), -1LI ($V_{CCINT} = 0.72V$)		

Table 26: Speed Grade Designations by Device (Cont'd)

Device	Speed Grade, Temperature Ranges, and V _{CCINT} Operating Voltages		
	Advance	Preliminary	Production
XCZU5EG	-3E (V _{CCINT} = 0.90V), -2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V), -2LE (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V), -1I (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V), -1LI (V _{CCINT} = 0.72V)		
XCZU5EV	-3E (V _{CCINT} = 0.90V), -2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V), -2LE (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V), -1I (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V), -1LI (V _{CCINT} = 0.72V)		
XCZU6CG	-2LE (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V) -1LI (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.72V)		-2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V) -1I (V _{CCINT} = 0.85V)
XCZU6EG	-3E (V _{CCINT} = 0.90V) -2LE (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V) -1LI (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.72V)		-2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V) -1I (V _{CCINT} = 0.85V)
XCZU7CG	-2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V), -2LE (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V), -1I (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V), -1LI (V _{CCINT} = 0.72V)		
XCZU7EG	-3E (V _{CCINT} = 0.90V), -2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V), -2LE (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V), -1I (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V), -1LI (V _{CCINT} = 0.72V)		
XCZU7EV	-3E (V _{CCINT} = 0.90V), -2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V), -2LE (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V), -1I (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V), -1LI (V _{CCINT} = 0.72V)		
XCZU9CG	-2LE (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V) -1LI (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.72V)		-2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V) -1I (V _{CCINT} = 0.85V)
XCZU9EG	-3E (V _{CCINT} = 0.90V) -2LE (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V) -1LI (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.72V)		-2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V) -1I (V _{CCINT} = 0.85V)

Table 30: PS DDR Performance (Cont'd)

Memory Standard	Package	DRAM Type	Speed Grade						Units
			-3		-2		-1		
			Min	Max	Min	Max	Min	Max	
DDR3	All FFV packages, FBVB900 and SFVC784	Single rank component	664	2133	664	2133	664	2133	Mb/s
		1 rank DIMM ⁽¹⁾⁽²⁾	664	1866	664	1866	664	1866	Mb/s
		2 rank DIMM ⁽¹⁾⁽³⁾	664	1600	664	1600	664	1600	Mb/s
	SFVA625	Single rank component	664	1866	664	1866	664	1866	Mb/s
		1 rank DIMM ⁽¹⁾⁽²⁾	664	1600	664	1600	664	1600	Mb/s
		2 rank DIMM ⁽¹⁾⁽³⁾	664	1333	664	1333	664	1333	Mb/s
	SBVA484	Single rank component	664	1066	664	1066	664	1066	Mb/s
		1 rank DIMM ⁽¹⁾⁽²⁾	664	1066	664	1066	664	1066	Mb/s
		2 rank DIMM ⁽¹⁾⁽³⁾	664	1066	664	1066	664	1066	Mb/s
DDR3L	All FFV packages, FBVB900 and SFVC784	Single rank component	664	1866	664	1866	664	1866	Mb/s
		1 rank DIMM ⁽¹⁾⁽²⁾	664	1600	664	1600	664	1600	Mb/s
		2 rank DIMM ⁽¹⁾⁽³⁾	664	1333	664	1333	664	1333	Mb/s
	SFVA625	Single rank component	664	1600	664	1600	664	1600	Mb/s
		1 rank DIMM ⁽¹⁾⁽²⁾	664	1333	664	1333	664	1333	Mb/s
		2 rank DIMM ⁽¹⁾⁽³⁾	664	1066	664	1066	664	1066	Mb/s
	SBVA484	Single rank component	664	1066	664	1066	664	1066	Mb/s
		1 rank DIMM ⁽¹⁾⁽²⁾	664	1066	664	1066	664	1066	Mb/s
		2 rank DIMM ⁽¹⁾⁽³⁾	664	1066	664	1066	664	1066	Mb/s
LPDDR3	All FFV packages, FBVB900 and SFVC784	Single die package ⁽⁶⁾	664	1600	664	1600	664	1600	Mb/s
		Dual die package ⁽⁶⁾	664	1333	664	1333	664	1333	Mb/s
	SFVA625	Single die package ⁽⁶⁾	664	1333	664	1333	664	1333	Mb/s
		Dual die package ⁽⁶⁾	664	1066	664	1066	664	1066	Mb/s
	SBVA484	Single die package ⁽⁶⁾	664	1066	664	1066	664	1066	Mb/s
		Dual die package ⁽⁶⁾	664	1066	664	1066	664	1066	Mb/s

Notes:

1. Dual in-line memory module (DIMM) includes RDIMM, SODIMM, and UDIMM.
2. Includes: 1 rank 1 slot, dual-die package 2 rank.
3. Includes: 2 rank 1 slot.
4. Dual die package includes single die with ECC.
5. LPDDR4 support is only available as a 32-bit interface.
6. 64-bit LPDDR3 interface performance values are defined without ECC support.

Table 37: PS Reset Assertion Timing Requirements

Symbol	Description	Min	Typ	Max	Units
T _{PSPOR}	Required PS_POR_B assertion time. ⁽¹⁾	10	–	–	μs
T _{PSRST}	Required PS_SRST_B assertion time.	3	–	–	PS_REF_CLK Clock Cycles

Notes:

1. PS_POR_B must be asserted Low at power-up and continue to be asserted for a duration of T_{PSPOR} after all the PS supply voltages reach minimum levels. PS_POR_B must be asserted Low for the duration of T_{POR} when the PS and PL power-up at the same time and the application uses both the PS and PL after power-up.

Table 38: PS Clocks Switching Characteristics

Symbol	Description	Speed Grade			Units
		-3	-2	-1	
F _{TOPSW_MAINMAX}	TOPSW_MAIN maximum frequency.	600	533	533	MHz
F _{TOPSW_LSBUSMAX}	TOPSW_LSBUS maximum frequency.	100	100	100	MHz
F _{GDMAMAX}	FPD-DMA maximum frequency.	600	600	600	MHz
F _{DPDMAMAX}	DisplayPort DMA maximum frequency.	600	600	600	MHz
F _{LPD_SWITCH_CTRLMAX}	LPD_SWITCH_CTRL maximum frequency.	600	500	500	MHz
F _{LPD_LSBUS_CTRLMAX}	LPD_LSBUS_CTRL maximum frequency.	100	100	100	MHz
F _{ADMAMAX}	LPD-DMA maximum frequency.	600	500	500	MHz
F _{APLL_TO_LPDMAX}	APLL_TO_LPD maximum frequency.	533	533	533	MHz
F _{DPDLL_TO_LPDMAX}	DPDLL_TO_LPD maximum frequency.	533	533	533	MHz
F _{VPDLL_TO_LPDMAX}	VPDLL_TO_LPD maximum frequency.	533	533	533	MHz
F _{IOPLL_TO_LPDMAX}	IOPLL_TO_LPD maximum frequency.	533	533	533	MHz
F _{RPLL_TO_FPDMAX}	RPLL_TO_FPD maximum frequency.	533	533	533	MHz

PS I2C Controller Interface

 Table 47: I2C Interface⁽¹⁾

Symbol	Description	Min	Max	Units
I2C Fast-mode Interface				
$T_{I2CFCKL}$	SCL Low time.	1.3	–	μ s
$T_{I2CFCKH}$	SCL High time.	0.6	–	μ s
$T_{I2CFCKO}$	SDA clock to out delay.	–	900	ns
$T_{I2CFDCK}$	SDA input setup time.	100	–	ns
$F_{I2CFCLK}$	SCL clock frequency.	–	400	KHz
I2C Standard-mode Interface				
$T_{I2CSCKL}$	SCL Low time.	4.7	–	μ s
$T_{I2CSCKH}$	SCL High time.	4.0	–	μ s
$T_{I2CSCKO}$	SDA clock to out delay.	–	3450	ns
$T_{I2CSDCK}$	SDA input setup time.	250	–	ns
$F_{I2CSCLK}$	SCL clock frequency.	–	100	KHz

Notes:

1. The test conditions are configured to the LVCMOS 3.3V I/O standard with a 12 mA drive strength, fast slew rate, and a 15 pF load.

PS SPI Controller Interface

 Table 48: SPI Interfaces⁽¹⁾

Symbol	Description	Min	Max	Units
SPI Master Interface				
$T_{DCMSPICLK}$	SPI master mode clock duty cycle.	45	55	%
$T_{MSPISSCLK}$	Slave select asserted to first active clock edge.	1 ⁽²⁾	–	$F_{SPI_REF_CLK}$ cycles
$T_{MSPISCLKSS}$	Last active clock edge to slave select deasserted.	1 ⁽²⁾	–	$F_{SPI_REF_CLK}$ cycles
$T_{MSPIDCK}$	Input setup time for MISO.	–2.0	–	ns
$T_{MSPICKD}$	Input hold time for MISO.	0.3	–	$F_{MSPICLK}$ cycles
$T_{MSPICKO}$	MOSI and slave select clock to out delay.	–2.0	5.0	ns
$F_{MSPICLK}$	SPI master device clock frequency.	–	50	MHz
$F_{SPI_REF_CLK}$	SPI reference clock frequency.	–	200	MHz
SPI Slave Interface				
$T_{SSPISCLK}$	Slave select asserted to first active clock edge.	2	–	$F_{SPI_REF_CLK}$ cycles
$T_{SSPISCLKSS}$	Last active clock edge to slave select deasserted.	2	–	$F_{SPI_REF_CLK}$ cycles
$T_{SSPIDCK}$	Input setup time for MOSI.	5.0	–	ns
$T_{SSPICKD}$	Input hold time for MOSI.	1	–	$F_{SPI_REF_CLK}$ cycles
$T_{SSPICKO}$	MISO clock to out delay.	0.0	13.0	ns
F_{SSPICK}	SPI slave mode device clock frequency.	–	25	MHz
$F_{SPI_REF_CLK}$	SPI reference clock frequency.	–	200	MHz

Notes:

1. The test conditions are configured to the LVCMOS 3.3V I/O standard with a 12 mA drive strength, fast slew rate, and a 30 pF load.
2. Valid when two SPI_REF_CLK delays are programmed between CS and CLK for $T_{MSPISSCLK}$, and between CLK and CS for $T_{MSPISCLKSS}$ in the SPI delay_reg0 register.

PS CAN Controller Interface

 Table 49: CAN Interface⁽¹⁾

Symbol	Description	Min	Max	Units
$T_{PWCANRX}$	Receive pulse width.	1.0	–	μs
$T_{PWCANTX}$	Transmit pulse width.	1.0	–	μs
$F_{CAN_REF_CLK}$	Internally sourced CAN reference clock frequency.	–	100	MHz
	Externally sourced CAN reference clock frequency.	–	40	MHz

Notes:

1. The test conditions are configured to the LVCMOS 3.3V I/O standard with a 12 mA drive strength, fast slew rate, and a 15 pF load.

PS-GTR Transceiver

Table 56: PS-GTR Transceiver DC Specifications

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
DV _{PPIN}	Differential peak-to-peak input voltage (external AC coupled).		100	–	1200	mV
V _{IN}	Single-ended input voltage. Voltage measured at the pin referenced to GND.		75	–	V _{PS_MGTRAVCC}	mV
V _{CMIN}	Common mode input voltage.		–	0	–	mV
DV _{PPOUT}	Differential peak-to-peak output voltage. ⁽¹⁾	Transmitter output swing is set to maximum value.	800	–	–	mV
V _{CMOUTAC}	Common mode output voltage: AC coupled (equation based).		$V_{PS_MGTRAVCC} - D_{VPPOUT}/2$			mV
R _{IN}	Differential input resistance.		–	100	–	Ω
R _{OUT}	Differential output resistance.		–	100	–	Ω
R _{MGTRREF}	Resistor value between calibration resistor pin to GND.		497.5	500	502.5	Ω
T _{OSKEW}	Transmitter output pair (TXP and TXN) intra-pair skew (All packages).		–	–	20	ps
C _{EXT}	Recommended external AC coupling capacitor. ⁽²⁾		–	100	–	nF

Notes:

1. The output swing and pre-emphasis levels are programmable using the attributes discussed in the *Zynq UltraScale+ MPSoC Technical Reference Manual (UG1085)*, and can result in values lower than reported in this table.
2. Other values can be used as appropriate to conform to specific protocols and standards.

Table 57: PS-GTR Transceiver Clock DC Input Level Specification

Symbol	DC Parameter	Min	Typ	Max	Units
V _{IDIFF}	Differential peak-to-peak input voltage.	250	–	2000	mV
R _{IN}	Differential input resistance.	–	100	–	Ω
C _{EXT}	Required external AC coupling capacitor.	–	10	–	nF

Table 58: PS-GTR Transceiver Performance

Symbol	Description	Speed Grade			Units
		-3	-2	-1	
F _{GTRMAX}	PS-GTR maximum line rate.	6.0	6.0	6.0	Gb/s
F _{GTRMIN}	PS-GTR minimum line rate.	1.25	1.25	1.25	Gb/s

Table 59: PS-GTR Transceiver PLL/Lock Time Adaptation

Symbol	Description	Min	Typ	Max	Units
T _{LOCK}	Initial PLL lock.	–	–	0.11	ms
T _{DLOCK}	Clock recovery phase acquisition and adaptation time.	–	–	24 x 10 ⁶	UI

Table 61: PS-GTR Transceiver Reference Clock Oscillator Selection Phase Noise Mask

Symbol	Description	Offset Frequency	Min	Typ	Max	Units
PLL _{REFCLKMASK}	PLL reference clock select phase noise mask at REFCLK frequency = 25 MHz.	100	–	–	–102	dBc/Hz
		1 KHz	–	–	–124	
		10 KHz	–	–	–132	
		100 KHz	–	–	–139	
		1 MHz	–	–	–152	
		10 MHz	–	–	–154	
	PLL reference clock select phase noise mask at REFCLK frequency = 50 MHz.	100	–	–	–96	dBc/Hz
		1 KHz	–	–	–118	
		10 KHz	–	–	–126	
		100 KHz	–	–	–133	
		1 MHz	–	–	–146	
	PLL reference clock select phase noise mask at REFCLK frequency = 100 MHz.	100	–	–	–90	dBc/Hz
		1 KHz	–	–	–112	
		10 KHz	–	–	–120	
		100 KHz	–	–	–127	
		1 MHz	–	–	–140	
	PLL reference clock select phase noise mask at REFCLK frequency = 125 MHz.	100	–	–	–88	dBc/Hz
		1 KHz	–	–	–110	
		10 KHz	–	–	–118	
		100 KHz	–	–	–125	
1 MHz		–	–	–138		
PLL reference clock select phase noise mask at REFCLK frequency = 150 MHz.	100	–	–	–86	dBc/Hz	
	1 KHz	–	–	–108		
	10 KHz	–	–	–116		
	100 KHz	–	–	–123		
	1 MHz	–	–	–136		
		10 MHz	–	–	–138	

Notes:

- For reference clock frequencies not in this table, use the phase noise mask for the nearest reference clock frequency.

Table 62: PS-GTR Transceiver Transmitter Switching Characteristics

Symbol	Description	Condition	Min	Typ	Max	Units
F _{GTRTX}	Serial data rate range.		1.25	–	6.0	Gb/s
T _{RTX}	TX rise time.	20%–80%	–	65	–	ps
T _{FTX}	TX fall time.	80%–20%	–	65	–	ps

Table 72: MIPI D-PHY Performance

Description	I/O Bank Type	Speed Grade and V _{CCINT} Operating Voltages					Units
		0.90V	0.85V		0.72V		
		-3 ⁽¹⁾	-2 ⁽¹⁾	-1	-2	-1	
MIPI D-PHY transmitter or receiver.	HP	1500	1500	1260	1260	1260	Mb/s

Notes:

1. In the SBVA484 package, the data rate is 1260 Mb/s.

Table 73: LVDS Native-Mode 1000BASE-X Support⁽¹⁾

Description	I/O Bank Type	Speed Grade and V _{CCINT} Operating Voltages				
		0.90V	0.85V		0.72V	
		-3	-2	-1	-2	-1
1000BASE-X	HP	Yes				

Notes:

1. 1000BASE-X support is based on the *IEEE Standard for CSMA/CD Access Method and Physical Layer Specifications* (IEEE Std 802.3-2008).

Table 74 provides the maximum data rates for applicable memory standards using the Zynq UltraScale+ MPSoC memory PHY. Refer to [Memory Interfaces](#) for the complete list of memory interface standards supported and detailed specifications. The final performance of the memory interface is determined through a complete design implemented in the Vivado Design Suite, following guidelines in the *UltraScale Architecture PCB Design Guide* ([UG583](#)), electrical analysis, and characterization of the system.

Table 74: Maximum Physical Interface (PHY) Rate for Memory Interfaces

Memory Standard	Package ⁽¹⁾	DRAM Type	Speed Grade and V _{CCINT} Operating Voltages					Units
			0.90V	0.85V		0.72V		
			-3	-2	-1	-2	-1	
DDR4	All FFV packages and FBVB900	Single rank component	2666	2666	2400	2400	2133	Mb/s
		1 rank DIMM ⁽²⁾⁽³⁾⁽⁴⁾	2400	2400	2133	2133	1866	Mb/s
		2 rank DIMM ⁽²⁾⁽⁵⁾	2133	2133	1866	1866	1600	Mb/s
		4 rank DIMM ⁽²⁾⁽⁶⁾	1600	1600	1333	1333	N/A	Mb/s
	SFVC784	Single rank component	2400	2400	2133	2133	1866	Mb/s
		1 rank DIMM ⁽²⁾⁽³⁾	2133	2133	1866	1866	1600	Mb/s
DDR3	All FFV packages and FBVB900	Single rank component	2133	2133	2133	2133	1866	Mb/s
		1 rank DIMM ⁽²⁾⁽³⁾	1866	1866	1866	1866	1600	Mb/s
		2 rank DIMM ⁽²⁾⁽⁵⁾	1600	1600	1600	1600	1333	Mb/s
		4 rank DIMM ⁽²⁾⁽⁶⁾	1066	1066	1066	1066	800	Mb/s
	SFVC784	Single rank component	1866	1866	1866	1866	1600	Mb/s
		1 rank DIMM ⁽²⁾⁽³⁾	1600	1600	1600	1600	1600	Mb/s
		2 rank DIMM ⁽²⁾⁽⁵⁾	1600	1600	1600	1600	1333	Mb/s
		4 rank DIMM ⁽²⁾⁽⁶⁾	1066	1066	1066	1066	800	Mb/s

Table 76: IOB High Performance (HP) Switching Characteristics (Cont'd)

I/O Standards	T _{INBUF_DELAY_PAD_I}					T _{OUTBUF_DELAY_O_PAD}					T _{OUTBUF_DELAY_TD_PAD}					Units
	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	
	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	
DIFF_SSTL12_F	0.394	0.394	0.402	0.394	0.402	0.412	0.412	0.430	0.412	0.430	0.538	0.538	0.566	0.538	0.566	ns
DIFF_SSTL12_M	0.394	0.394	0.402	0.394	0.402	0.553	0.553	0.584	0.553	0.584	0.641	0.641	0.676	0.641	0.676	ns
DIFF_SSTL12_S	0.394	0.394	0.402	0.394	0.402	0.758	0.758	0.808	0.758	0.808	0.823	0.823	0.879	0.823	0.879	ns
DIFF_SSTL135_DCI_F	0.371	0.371	0.402	0.371	0.402	0.411	0.411	0.428	0.411	0.428	0.537	0.537	0.565	0.537	0.565	ns
DIFF_SSTL135_DCI_M	0.371	0.371	0.402	0.371	0.402	0.551	0.551	0.582	0.551	0.582	0.645	0.645	0.685	0.645	0.685	ns
DIFF_SSTL135_DCI_S	0.371	0.371	0.402	0.371	0.402	0.746	0.746	0.799	0.746	0.799	0.829	0.829	0.893	0.829	0.893	ns
DIFF_SSTL135_F	0.375	0.375	0.402	0.375	0.402	0.408	0.408	0.428	0.408	0.428	0.528	0.528	0.561	0.528	0.561	ns
DIFF_SSTL135_M	0.375	0.375	0.402	0.375	0.402	0.555	0.555	0.585	0.555	0.585	0.641	0.641	0.679	0.641	0.679	ns
DIFF_SSTL135_S	0.375	0.375	0.402	0.375	0.402	0.772	0.772	0.823	0.772	0.823	0.827	0.827	0.878	0.827	0.878	ns
DIFF_SSTL15_DCI_F	0.397	0.397	0.417	0.397	0.417	0.412	0.412	0.429	0.412	0.429	0.531	0.531	0.563	0.531	0.563	ns
DIFF_SSTL15_DCI_M	0.397	0.397	0.417	0.397	0.417	0.553	0.553	0.583	0.553	0.583	0.645	0.645	0.685	0.645	0.685	ns
DIFF_SSTL15_DCI_S	0.397	0.397	0.417	0.397	0.417	0.768	0.768	0.822	0.768	0.822	0.847	0.847	0.912	0.847	0.912	ns
DIFF_SSTL15_F	0.404	0.404	0.417	0.404	0.417	0.424	0.424	0.445	0.424	0.445	0.551	0.551	0.577	0.551	0.577	ns
DIFF_SSTL15_M	0.404	0.404	0.417	0.404	0.417	0.554	0.554	0.585	0.554	0.585	0.639	0.639	0.677	0.639	0.677	ns
DIFF_SSTL15_S	0.404	0.404	0.417	0.404	0.417	0.767	0.767	0.817	0.767	0.817	0.813	0.813	0.867	0.813	0.867	ns
DIFF_SSTL18_I_DCI_F	0.320	0.320	0.336	0.320	0.336	0.445	0.445	0.461	0.445	0.461	0.566	0.566	0.595	0.566	0.595	ns
DIFF_SSTL18_I_DCI_M	0.320	0.320	0.336	0.320	0.336	0.554	0.554	0.585	0.554	0.585	0.644	0.644	0.683	0.644	0.683	ns
DIFF_SSTL18_I_DCI_S	0.320	0.320	0.336	0.320	0.336	0.762	0.762	0.818	0.762	0.818	0.837	0.837	0.899	0.837	0.899	ns
DIFF_SSTL18_I_F	0.316	0.316	0.336	0.316	0.336	0.454	0.454	0.476	0.454	0.476	0.578	0.578	0.608	0.578	0.608	ns
DIFF_SSTL18_I_M	0.316	0.316	0.336	0.316	0.336	0.571	0.571	0.603	0.571	0.603	0.652	0.652	0.692	0.652	0.692	ns
DIFF_SSTL18_I_S	0.316	0.316	0.336	0.316	0.336	0.782	0.782	0.835	0.782	0.835	0.816	0.816	0.870	0.816	0.870	ns
HSLVDCI_15_F	0.393	0.393	0.415	0.393	0.415	0.425	0.425	0.443	0.425	0.443	0.548	0.548	0.579	0.548	0.579	ns
HSLVDCI_15_M	0.393	0.393	0.415	0.393	0.415	0.552	0.552	0.581	0.552	0.581	0.644	0.644	0.684	0.644	0.684	ns
HSLVDCI_15_S	0.393	0.393	0.415	0.393	0.415	0.748	0.748	0.802	0.748	0.802	0.827	0.827	0.890	0.827	0.890	ns
HSLVDCI_18_F	0.424	0.424	0.447	0.424	0.447	0.445	0.445	0.461	0.445	0.461	0.566	0.566	0.595	0.566	0.595	ns
HSLVDCI_18_M	0.424	0.424	0.447	0.424	0.447	0.567	0.567	0.598	0.567	0.598	0.658	0.658	0.699	0.658	0.699	ns
HSLVDCI_18_S	0.424	0.424	0.447	0.424	0.447	0.761	0.761	0.817	0.761	0.817	0.836	0.836	0.900	0.836	0.900	ns
HSTL_I_12_F	0.378	0.378	0.399	0.378	0.399	0.423	0.423	0.443	0.423	0.443	0.553	0.553	0.582	0.553	0.582	ns
HSTL_I_12_M	0.378	0.378	0.399	0.378	0.399	0.551	0.551	0.582	0.551	0.582	0.642	0.642	0.679	0.642	0.679	ns
HSTL_I_12_S	0.378	0.378	0.399	0.378	0.399	0.750	0.750	0.799	0.750	0.799	0.813	0.813	0.868	0.813	0.868	ns
HSTL_I_18_F	0.322	0.322	0.339	0.322	0.339	0.456	0.456	0.474	0.456	0.474	0.576	0.576	0.606	0.576	0.606	ns
HSTL_I_18_M	0.322	0.322	0.339	0.322	0.339	0.569	0.569	0.602	0.569	0.602	0.653	0.653	0.692	0.653	0.692	ns
HSTL_I_18_S	0.322	0.322	0.339	0.322	0.339	0.781	0.781	0.833	0.781	0.833	0.816	0.816	0.871	0.816	0.871	ns
HSTL_I_DCI_12_F	0.378	0.378	0.399	0.378	0.399	0.406	0.406	0.429	0.406	0.429	0.534	0.534	0.564	0.534	0.564	ns
HSTL_I_DCI_12_M	0.378	0.378	0.399	0.378	0.399	0.556	0.556	0.586	0.556	0.586	0.654	0.654	0.694	0.654	0.694	ns
HSTL_I_DCI_12_S	0.378	0.378	0.399	0.378	0.399	0.754	0.754	0.803	0.754	0.803	0.842	0.842	0.907	0.842	0.907	ns
HSTL_I_DCI_18_F	0.321	0.321	0.339	0.321	0.339	0.445	0.445	0.461	0.445	0.461	0.566	0.566	0.595	0.566	0.595	ns
HSTL_I_DCI_18_M	0.321	0.321	0.339	0.321	0.339	0.554	0.554	0.585	0.554	0.585	0.643	0.643	0.684	0.643	0.684	ns
HSTL_I_DCI_18_S	0.321	0.321	0.339	0.321	0.339	0.761	0.761	0.817	0.761	0.817	0.836	0.836	0.900	0.836	0.900	ns
HSTL_I_DCI_F	0.393	0.393	0.415	0.393	0.415	0.431	0.431	0.445	0.431	0.445	0.555	0.555	0.575	0.555	0.575	ns
HSTL_I_DCI_M	0.393	0.393	0.415	0.393	0.415	0.552	0.552	0.581	0.552	0.581	0.644	0.644	0.684	0.644	0.684	ns

Table 79: Output Delay Measurement Methodology

Description	I/O Standard Attribute	R _{REF} (Ω)	C _{REF} ⁽¹⁾ (pF)	V _{MEAS} (V)	V _{REF} (V)
LVC MOS, 1.2V	LVC MOS12	1M	0	0.6	0
LVC MOS, 1.5V	LVC MOS15	1M	0	0.75	0
LVC MOS, 1.8V	LVC MOS18	1M	0	0.9	0
LVC MOS, 2.5V	LVC MOS25	1M	0	1.25	0
LVC MOS, 3.3V	LVC MOS33	1M	0	1.65	0
LVTTL, 3.3V	LVTTL	1M	0	1.65	0
LVDCI, HSLVDCI, 1.5V	LVDCI_15, HSLVDCI_15	50	0	V _{REF}	0.75
LVDCI, HSLVDCI, 1.8V	LVDCI_15, HSLVDCI_18	50	0	V _{REF}	0.9
HSTL (high-speed transceiver logic), class I, 1.2V	HSTL_I_12	50	0	V _{REF}	0.6
HSTL, class I, 1.5V	HSTL_I	50	0	V _{REF}	0.75
HSTL, class I, 1.8V	HSTL_I_18	50	0	V _{REF}	0.9
HSUL (high-speed unterminated logic), 1.2V	HSUL_12	50	0	V _{REF}	0.6
SSTL12 (stub series terminated logic), 1.2V	SSTL12	50	0	V _{REF}	0.6
SSTL135 and SSTL135 class II, 1.35V	SSTL135, SSTL135_II	50	0	V _{REF}	0.675
SSTL15 and SSTL15 class II, 1.5V	SSTL15, SSTL15_II	50	0	V _{REF}	0.75
SSTL18, class I and class II, 1.8V	SSTL18_I, SSTL18_II	50	0	V _{REF}	0.9
POD10, 1.0V	POD10	50	0	V _{REF}	1.0
POD12, 1.2V	POD12	50	0	V _{REF}	1.2
DIFF_HSTL, class I, 1.2V	DIFF_HSTL_I_12	50	0	V _{REF}	0.6
DIFF_HSTL, class I, 1.5V	DIFF_HSTL_I	50	0	V _{REF}	0.75
DIFF_HSTL, class I, 1.8V	DIFF_HSTL_I_18	50	0	V _{REF}	0.9
DIFF_HSUL, 1.2V	DIFF_HSUL_12	50	0	V _{REF}	0.6
DIFF_SSTL12, 1.2V	DIFF_SSTL12	50	0	V _{REF}	0.6
DIFF_SSTL135 and DIFF_SSTL135 class II, 1.35V	DIFF_SSTL135, DIFF_SSTL135_II	50	0	V _{REF}	0.675
DIFF_SSTL15 and DIFF_SSTL15 class II, 1.5V	DIFF_SSTL15, DIFF_SSTL15_II	50	0	V _{REF}	0.75
DIFF_SSTL18, class I and II, 1.8V	DIFF_SSTL18_I, DIFF_SSTL18_II	50	0	V _{REF}	0.9
DIFF_POD10, 1.0V	DIFF_POD10	50	0	V _{REF}	1.0
DIFF_POD12, 1.2V	DIFF_POD12	50	0	V _{REF}	1.2
LVDS (low-voltage differential signaling), 1.8V	LVDS	100	0	0 ⁽²⁾	0
SUB_LVDS, 1.8V	SUB_LVDS	100	0	0 ⁽²⁾	0
MIPI D-PHY (high speed) 1.2V	MIPI_DPHY_DCI_HS	100	0	0 ⁽²⁾	0
MIPI D-PHY (low power) 1.2V	MIPI_DPHY_DCI_LP	1M	0	0.6	0

Notes:

1. C_{REF} is the capacitance of the probe, nominally 0 pF.
2. The value given is the differential output voltage.

PLL Switching Characteristics

 Table 86: PLL Specification⁽¹⁾

Symbol	Description	Speed Grade and V _{CCINT} Operating Voltages					Units
		0.90V	0.85V		0.72V		
		-3	-2	-1	-2	-1	
PLL_F _{INMAX}	Maximum input clock frequency.	1066	933	800	933	800	MHz
PLL_F _{INMIN}	Minimum input clock frequency.	70	70	70	70	70	MHz
PLL_F _{INJITTER}	Maximum input clock period jitter.	< 20% of clock input period or 1 ns Max					
PLL_F _{INDUTY}	Input duty cycle range: 70–399 MHz.	35–65					%
	Input duty cycle range: 400–499 MHz.	40–60					%
	Input duty cycle range: >500 MHz.	45–55					%
PLL_F _{VCOMIN}	Minimum PLL VCO frequency.	750	750	750	750	750	MHz
PLL_F _{VCOMAX}	Maximum PLL VCO frequency.	1500	1500	1500	1500	1500	MHz
PLL_T _{STATPHAOFFSET}	Static phase offset of the PLL outputs. ⁽²⁾	0.12	0.12	0.12	0.12	0.12	ns
PLL_T _{OUTJITTER}	PLL output jitter.	Note 3					
PLL_T _{OUTDUTY}	PLL CLKOUT0, CLKOUT0B, CLKOUT1, CLKOUT1B duty-cycle precision. ⁽⁴⁾	0.165	0.20	0.20	0.20	0.20	ns
PLL_T _{LOCKMAX}	PLL maximum lock time.	100					µs
PLL_F _{OUTMAX}	PLL maximum output frequency at CLKOUT0, CLKOUT0B, CLKOUT1, CLKOUT1B.	891	775	667	725	667	MHz
	PLL maximum output frequency at CLKOUTPHY.	2667	2667	2400	2400	2133	MHz
PLL_F _{OUTMIN}	PLL minimum output frequency at CLKOUT0, CLKOUT0B, CLKOUT1, CLKOUT1B. ⁽⁵⁾	5.86	5.86	5.86	5.86	5.86	MHz
	PLL minimum output frequency at CLKOUTPHY.	2 x VCO mode: 1500, 1 x VCO mode: 750 0.5 x VCO mode: 375					MHz
PLL_RST _{MINPULSE}	Minimum reset pulse width.	5.00	5.00	5.00	5.00	5.00	ns
PLL_F _{PFDMAX}	Maximum frequency at the phase frequency detector.	667.5	667.5	667.5	667.5	667.5	MHz
PLL_F _{PFDMIN}	Minimum frequency at the phase frequency detector.	70	70	70	70	70	MHz
PLL_F _{BANDWIDTH}	PLL bandwidth at typical.	14	14	14	14	14	MHz
PLL_F _{DPRCLK_MAX}	Maximum DRP clock frequency	250	250	250	250	250	MHz

Notes:

1. The PLL does not filter typical spread-spectrum input clocks because they are usually far below the loop filter frequencies.
2. The static offset is measured between any PLL outputs with identical phase.
3. Values for this parameter are available in the Clocking Wizard.
4. Includes global clock buffer.
5. Calculated as F_{VCO}/128 assuming output duty cycle is 50%.

Table 88: Global Clock Input to Output Delay Without MMCM (Far Clock Region)

Symbol	Description	Device	Speed Grade and V _{CCINT} Operating Voltages					Units
			0.90V	0.85V		0.72V		
			-3	-2	-1	-2	-1	
SSTL15 Global Clock Input to Output Delay using Output Flip-Flop, Fast Slew Rate, without MMCM.								
T _{ICKOF_FAR}	Global clock input and output flip-flop without MMCM (far clock region).	XCZU2	N/A	5.27	5.68	5.80	6.13	ns
		XCZU3	N/A	5.27	5.68	5.80	6.13	ns
		XCZU4	5.07	6.06	6.61	6.23	7.10	ns
		XCZU5	5.07	6.06	6.61	6.23	7.10	ns
		XCZU6	5.38	6.49	6.97	7.14	7.59	ns
		XCZU7	5.39	6.54	7.01	7.16	7.62	ns
		XCZU9	5.38	6.49	6.97	7.14	7.59	ns
		XCZU11	6.18	7.41	8.11	7.66	8.99	ns
		XCZU15	5.38	6.49	6.96	7.19	7.71	ns
		XCZU17	6.21	7.53	8.07	8.36	8.90	ns
XCZU19	6.21	7.53	8.07	8.36	8.90	ns		

Notes:

1. This table lists representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible I/O and CLB flip-flops are clocked by the global clock net.

Table 89: Global Clock Input to Output Delay With MMCM

Symbol	Description	Device	Speed Grade and V _{CCINT} Operating Voltages					Units
			0.90V	0.85V		0.72V		
			-3	-2	-1	-2	-1	
SSTL15 Global Clock Input to Output Delay using Output Flip-Flop, Fast Slew Rate, with MMCM.								
T _{ICKOFMMCMCC}	Global clock input and output flip-flop with MMCM.	XCZU2	N/A	2.22	2.43	2.96	2.94	ns
		XCZU3	N/A	2.22	2.43	2.96	2.94	ns
		XCZU4	2.47	2.47	2.78	3.04	3.35	ns
		XCZU5	2.47	2.47	2.78	3.04	3.35	ns
		XCZU6	2.15	2.15	2.36	2.86	2.86	ns
		XCZU7	2.32	2.32	2.57	3.06	3.13	ns
		XCZU9	2.15	2.15	2.36	2.86	2.86	ns
		XCZU11	2.64	2.64	2.96	3.25	3.55	ns
		XCZU15	2.18	2.18	2.38	2.88	2.90	ns
		XCZU17	2.44	2.44	2.66	3.19	3.17	ns
XCZU19	2.44	2.44	2.66	3.19	3.17	ns		

Notes:

1. This table lists representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible I/O and CLB flip-flops are clocked by the global clock net.
2. MMCM output jitter is already included in the timing calculation.

Device Pin-to-Pin Input Parameter Guidelines

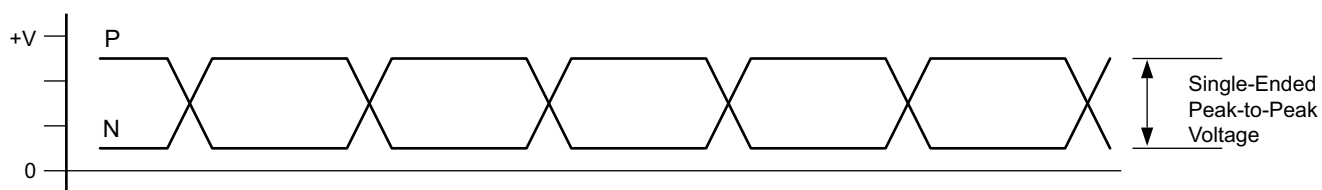
The pin-to-pin numbers in [Table 90](#) and [Table 91](#) are based on the clock root placement in the center of the device. The actual pin-to-pin values will vary if the root placement selected is different. Consult the Vivado Design Suite timing report for the actual pin-to-pin values.

Table 90: Global Clock Input Setup and Hold With 3.3V HD I/O without MMCM

Symbol	Description	Device	Speed Grade and V _{CCINT} Operating Voltages					Units	
			0.90V	0.85V		0.72V			
			-3	-2	-1	-2	-1		
Input Setup and Hold Time Relative to Global Clock Input Signal using SSTL15 Standard. ⁽¹⁾⁽²⁾⁽³⁾									
T _{PSFD_ZU2}	Global clock input and input flip-flop (or latch) without MMCM.	Setup	XCZU2	N/A	2.27	2.37	2.55	2.64	ns
T _{PHFD_ZU2}		Hold			-0.36	-0.36	-0.14	-0.14	ns
T _{PSFD_ZU3}		Setup	XCZU3	N/A	2.27	2.37	2.55	2.64	ns
T _{PHFD_ZU3}		Hold			-0.36	-0.36	-0.14	-0.14	ns
T _{PSFD_ZU4}		Setup	XCZU4	1.28	2.01	2.07	2.59	2.59	ns
T _{PHFD_ZU4}		Hold		-0.28	-0.28	-0.28	-0.09	-0.09	ns
T _{PSFD_ZU5}		Setup	XCZU5	1.28	2.01	2.07	2.59	2.59	ns
T _{PHFD_ZU5}		Hold		-0.28	-0.28	-0.28	-0.09	-0.09	ns
T _{PSFD_ZU6}		Setup	XCZU6	0.96	1.79	1.86	1.93	2.02	ns
T _{PHFD_ZU6}		Hold		-0.05	-0.05	-0.05	0.27	0.42	ns
T _{PSFD_ZU7}		Setup	XCZU7	1.43	2.32	2.42	2.60	2.69	ns
T _{PHFD_ZU7}		Hold		-0.40	-0.40	-0.40	-0.21	-0.21	ns
T _{PSFD_ZU9}		Setup	XCZU9	0.96	1.79	1.86	1.93	2.02	ns
T _{PHFD_ZU9}		Hold		-0.05	-0.05	-0.05	0.27	0.42	ns
T _{PSFD_ZU11}		Setup	XCZU11	1.28	2.01	2.07	2.59	2.59	ns
T _{PHFD_ZU11}		Hold		-0.29	-0.29	-0.29	-0.09	0.19	ns
T _{PSFD_ZU15}		Setup	XCZU15	0.96	1.79	1.85	1.92	2.01	ns
T _{PHFD_ZU15}		Hold		-0.04	-0.04	-0.04	0.27	0.43	ns
T _{PSFD_ZU17}		Setup	XCZU17	1.41	2.29	2.38	2.57	2.65	ns
T _{PHFD_ZU17}		Hold		-0.38	-0.38	-0.38	-0.19	-0.19	ns
T _{PSFD_ZU19}	Setup	XCZU19	1.41	2.29	2.38	2.57	2.65	ns	
T _{PHFD_ZU19}	Hold		-0.38	-0.38	-0.38	-0.19	-0.19	ns	

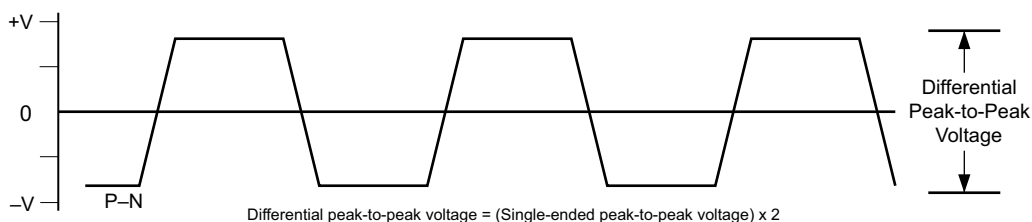
Notes:

1. Setup and hold times are measured over worst case conditions (process, voltage, temperature). Setup time is measured relative to the global clock input signal using the slowest process, slowest temperature, and slowest voltage. Hold time is measured relative to the global clock input signal using the fastest process, fastest temperature, and fastest voltage.
2. This table lists representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible I/O and CLB flip-flops are clocked by the global clock net.
3. Use IBIS to determine any duty-cycle distortion incurred using various standards.



X16653-101316

Figure 5: Single-Ended Peak-to-Peak Voltage



X16639-101316

Figure 6: Differential Peak-to-Peak Voltage

Table 107 and Table 108 summarize the DC specifications of the clock input of the GTY transceivers in Zynq UltraScale+ MPSoCs. Consult the *UltraScale Architecture GTY Transceiver User Guide (UG578)* for further details.

Table 107: GTY Transceiver Clock DC Input Level Specification

Symbol	DC Parameter	Min	Typ	Max	Units
V _{IDIFF}	Differential peak-to-peak input voltage	250	–	2000	mV
R _{IN}	Differential input resistance	–	100	–	Ω
C _{EXT}	Required external AC coupling capacitor	–	10	–	nF

Table 108: GTY Transceiver Clock Output Level Specification

Symbol	Description	Conditions	Min	Typ	Max	Units
V _{OL}	Output Low voltage for P and N	R _T = 100Ω across P and N signals	100	–	330	mV
V _{OH}	Output High voltage for P and N	R _T = 100Ω across P and N signals	500	–	700	mV
V _{DDOUT}	Differential output voltage (P–N), P = High (N–P), N = High	R _T = 100Ω across P and N signals	300	–	430	mV
V _{CMOUT}	Common mode voltage	R _T = 100Ω across P and N signals	300	–	500	mV

Table 113: GTY Transceiver PLL/Lock Time Adaptation

Symbol	Description	Conditions	All Speed Grades			Units
			Min	Typ	Max	
T _{LOCK}	Initial PLL lock.		–	–	1	ms
T _{DLOCK}	Clock recovery phase acquisition and adaptation time for decision feedback equalizer (DFE).	After the PLL is locked to the reference clock, this is the time it takes to lock the clock data recovery (CDR) to the data present at the input.	–	50,000	37 x 10 ⁶	UI
	Clock recovery phase acquisition and adaptation time for low-power mode (LPM) when the DFE is disabled.		–	50,000	2.3 x 10 ⁶	UI

Table 114: GTY Transceiver User Clock Switching Characteristics⁽¹⁾

Symbol	Description	Data Width Conditions (Bit)		Speed Grade and V _{CCINT} Operating Voltages					Units
				0.90V	0.85V		0.72V		
		Internal Logic	Interconnect Logic	-3 ⁽²⁾	-2 ⁽²⁾⁽³⁾	-1 ⁽⁴⁾⁽⁵⁾	-2 ⁽³⁾	-1 ⁽⁵⁾	
F _{TXOUTPMA}	TXOUTCLK maximum frequency sourced from OUTCLKPMA			511.719	511.719	402.833	402.833	322.266	MHz
F _{RXOUTPMA}	RXOUTCLK maximum frequency sourced from OUTCLKPMA			511.719	511.719	402.833	402.833	322.266	MHz
F _{TXOUTPROGDIV}	TXOUTCLK maximum frequency sourced from TXPROGDIVCLK			511.719	511.719	511.719	511.719	511.719	MHz
F _{RXOUTPROGDIV}	RXOUTCLK maximum frequency sourced from RXPROGDIVCLK			511.719	511.719	511.719	511.719	511.719	MHz
F _{TXIN}	TXUSRCLK ⁽⁶⁾ maximum frequency	16	16, 32	511.719	511.719	390.625	390.625	322.266	MHz
		32	32, 64	511.719	511.719	390.625	390.625	322.266	MHz
		64	64, 128	511.719	440.781	402.832	402.832	195.313	MHz
		20	20, 40	409.375	409.375	312.500	312.500	257.813	MHz
		40	40, 80	409.375	409.375	312.500	350.000	257.813	MHz
		80	80, 160	409.375	352.625	322.266	352.625	156.250	MHz
F _{RXIN}	RXUSRCLK ⁽⁶⁾ maximum frequency	16	16, 32	511.719	511.719	390.625	390.625	322.266	MHz
		32	32, 64	511.719	511.719	390.625	390.625	322.266	MHz
		64	64, 128	511.719	440.781	402.832	402.832	195.313	MHz
		20	20, 40	409.375	409.375	312.500	312.500	257.813	MHz
		40	40, 80	409.375	409.375	312.500	350.000	257.813	MHz
		80	80, 160	409.375	352.625	322.266	352.625	156.250	MHz

Table 115: GTY Transceiver Transmitter Switching Characteristics

Symbol	Description	Condition	Min	Typ	Max	Units
F _{GTYTX}	Serial data rate range		0.500	–	F _{GTYMAX}	Gb/s
T _{RTX}	TX rise time	20%–80%	–	21	–	ps
T _{FTX}	TX fall time	80%–20%	–	21	–	ps
T _{LLSKEW}	TX lane-to-lane skew ⁽¹⁾		–	–	500.00	ps
T _{J32.75}	Total jitter ⁽²⁾⁽⁴⁾	32.75 Gb/s	–	–	0.35	UI
D _{J32.75}	Deterministic jitter ⁽²⁾⁽⁴⁾		–	–	0.19	UI
T _{J28.21}	Total jitter ⁽²⁾⁽⁴⁾	28.21 Gb/s	–	–	0.28	UI
D _{J28.21}	Deterministic jitter ⁽²⁾⁽⁴⁾		–	–	0.17	UI
T _{J16.375}	Total jitter ⁽²⁾⁽⁴⁾	16.375 Gb/s	–	–	0.28	UI
D _{J16.375}	Deterministic jitter ⁽²⁾⁽⁴⁾		–	–	0.17	UI
T _{J15.0}	Total jitter ⁽²⁾⁽⁴⁾	15.0 Gb/s	–	–	0.28	UI
D _{J15.0}	Deterministic jitter ⁽²⁾⁽⁴⁾		–	–	0.17	UI
T _{J14.1}	Total jitter ⁽²⁾⁽⁴⁾	14.1 Gb/s	–	–	0.28	UI
D _{J14.1}	Deterministic jitter ⁽²⁾⁽⁴⁾		–	–	0.17	UI
T _{J14.1}	Total jitter ⁽²⁾⁽⁴⁾	14.025 Gb/s	–	–	0.28	UI
D _{J14.1}	Deterministic jitter ⁽²⁾⁽⁴⁾		–	–	0.17	UI
T _{J13.1}	Total jitter ⁽²⁾⁽⁴⁾	13.1 Gb/s	–	–	0.28	UI
D _{J13.1}	Deterministic jitter ⁽²⁾⁽⁴⁾		–	–	0.17	UI
T _{J12.5_QPLL}	Total jitter ⁽²⁾⁽⁴⁾	12.5 Gb/s	–	–	0.28	UI
D _{J12.5_QPLL}	Deterministic jitter ⁽²⁾⁽⁴⁾		–	–	0.17	UI
T _{J12.5_CPLL}	Total jitter ⁽³⁾⁽⁴⁾	12.5 Gb/s	–	–	0.33	UI
D _{J12.5_CPLL}	Deterministic jitter ⁽³⁾⁽⁴⁾		–	–	0.17	UI
T _{J11.3_QPLL}	Total jitter ⁽²⁾⁽⁴⁾	11.3 Gb/s	–	–	0.28	UI
D _{J11.3_QPLL}	Deterministic jitter ⁽²⁾⁽⁴⁾		–	–	0.17	UI
T _{J10.3125_QPLL}	Total jitter ⁽²⁾⁽⁴⁾	10.3125 Gb/s	–	–	0.28	UI
D _{J10.3125_QPLL}	Deterministic jitter ⁽²⁾⁽⁴⁾		–	–	0.17	UI
T _{J10.3125_CPLL}	Total jitter ⁽³⁾⁽⁴⁾	10.3125 Gb/s	–	–	0.33	UI
D _{J10.3125_CPLL}	Deterministic jitter ⁽³⁾⁽⁴⁾		–	–	0.17	UI
T _{J9.953_QPLL}	Total jitter ⁽²⁾⁽⁴⁾	9.953 Gb/s	–	–	0.28	UI
D _{J9.953_QPLL}	Deterministic jitter ⁽²⁾⁽⁴⁾		–	–	0.17	UI
T _{J9.953_CPLL}	Total jitter ⁽³⁾⁽⁴⁾	9.953 Gb/s	–	–	0.33	UI
D _{J9.953_CPLL}	Deterministic jitter ⁽³⁾⁽⁴⁾		–	–	0.17	UI
T _{J8.0}	Total jitter ⁽³⁾⁽⁴⁾	8.0 Gb/s	–	–	0.32	UI
D _{J8.0}	Deterministic jitter ⁽³⁾⁽⁴⁾		–	–	0.17	UI
T _{J6.6}	Total jitter ⁽³⁾⁽⁴⁾	6.6 Gb/s	–	–	0.30	UI
D _{J6.6}	Deterministic jitter ⁽³⁾⁽⁴⁾		–	–	0.15	UI
T _{J5.0}	Total jitter ⁽³⁾⁽⁴⁾	5.0 Gb/s	–	–	0.30	UI
D _{J5.0}	Deterministic jitter ⁽³⁾⁽⁴⁾		–	–	0.15	UI
T _{J4.25}	Total jitter ⁽³⁾⁽⁴⁾	4.25 Gb/s	–	–	0.30	UI
D _{J4.25}	Deterministic jitter ⁽³⁾⁽⁴⁾		–	–	0.15	UI

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